

**What Is Claimed Is:**

1. A method comprising bonding a chip module in a card body with an adhesive comprising at least two adhesive layers (i) and (ii), the at least two layers (i) and (ii) of the adhesive film differing chemically from one another.

2. The method of claim 1, wherein the adhesives of layers (i) and/or (ii) are pressure sensitive adhesives.

3. The method of claim 1, wherein layer (i) exhibits high bonding compatibility with epoxy materials and/or polyimides and layer (ii) exhibits high bonding compatibility with polycarbonate, polyethylene, polypropylene, acrylonitrile-butadiene-styrene copolymer plastics, polyethylene terephthalate and/or polyvinyl chloride.

4. The method of claim 1, wherein layer (i) is based on thermoplastic polymers.

5. The method of claim 4, wherein the thermoplastic polymers are selected from the group consisting of thermoplastic polymers based on polyesters, polyamides, copolyesters and/or copolyamides.

6. The method of claim 1, wherein layer (ii) is based on polyurethanes and/or rubbers.

7. The method of claim 6, wherein layer (ii) is based on synthetic rubbers.

8. The method of claim 1, wherein layer (ii) is based on heat-activatable systems.

9. The method of claim 8, wherein layer (ii) is based on a heat-activatable system composed of an elastomer and at least one reactive resin, wherein the elastomer is composed of at least one of rubbers, polychloroisoprenes, polyacrylates, nitrile rubbers and/or epoxidized nitrile rubbers and/or the reactive resin is composed of at least

one of phenolic resins, epoxy resins, melamine resins and/or resins with isocyanate function.

10. The method of claim 1, wherein between layer (i) and layer (ii) there are one or more further layers.

5           11. The method of claim 10, wherein the one or more further layers comprise one or more primer, barrier and/or carrier layers.

10           12. An adhesive unit consisting of a card body, an adhesive film and a chip module, wherein the adhesive film comprises at least two adhesive layers (i) and (ii), the at least two layers (i) and (ii) of the adhesive film differing chemically from one another.